

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): A semiconductor wafer obtained, at least, by removing a mechanical damage layer by etching both of opposite front and back surfaces of the wafer, flattening ~~one of the surfaces~~ the back surface by a surface-grinding means to the exclusion of the front surface of the wafer, polishing both of the front and back surfaces, and then subjecting ~~a the~~ front surface of the wafer to a finishing mirror-polishing when defining the surface subjected to surface-grinding as a the back surface of the wafer.

2-5. (Cancelled).

6. (Currently Amended): A semiconductor wafer, wherein the wafer has opposite front and back surfaces, the front surface is subjected to a finishing mirror-polishing without being subjected to surface-grinding, the back surface is subjected to surface-grinding, and micro roughness formed during surface-grinding remains on the back surface.

7. (Previously Presented): The semiconductor wafer according to claim 6, wherein the micro roughness on the back surface has P-V value of 30-50 nm and intervals of 1-10 nm.

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Amendments to the Drawings:

The attached sheet of drawings includes a change to FIG. 1 [B]. This sheet, which includes FIG. 1 [A] and [B], replaces the original sheet including FIG. 1 [A] and [B]. In FIG. 1 [B], the legend -- PRIOR ART -- has been added.

Attachment: Replacement Sheet